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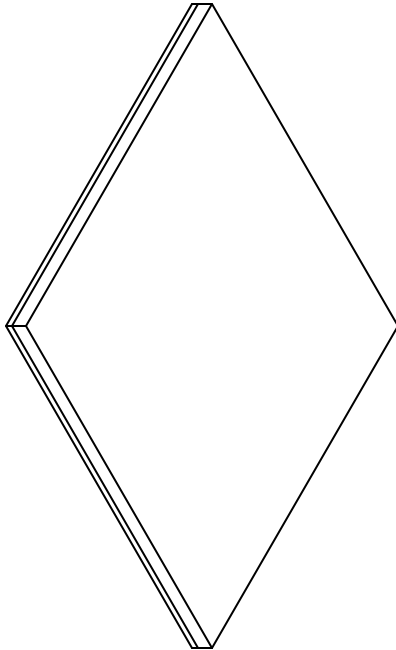
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REVISION HISTORY					
REV	REV NUMBER	DESCRIPTION	ORIGINATOR	INTEGRATOR	DATE
00	—	INITIAL RELEASE	SHIMJIB	SHIMJIB	01/05/04



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001—0531—2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001—0519—2082: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 961.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 31 X 31.
2. THE BASIC SOLDER BALL GRID PITCH IS 0.40mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M—1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS DECIMAL X.XX ±0.01 X.XX ±0.05 X.XX ±0.05 INTERPRET DIM AND TOL PER ASME Y14.5M - 1994		THIRD ANGLE PROJECTION		APPROVALS		DATE		TITLE		DATE		REV	
N/A		N/A		SHIMJIB		12/24/03		PACKAGE OUTLINE - MAF, 31 X 31 MATRIX, 13.00mm X 13.00mm X 0.86mm, 0.45mm MOLD CAP, 0.25mm BALL, 0.40mm PITCH, LAMINATE SUBSTRATE, AAWW		N/A		N/A	
N/A		N/A		WILLIE		12/24/03		SIZE		N/A		N/A	
N/A		N/A		PROJECT TRANS		12/24/03		REV		N/A		N/A	
N/A		N/A		JDKIM		01/08/04		N/A		N/A		N/A	

